CLEAN ROOM

- 500 m², ISO 5-8
- 100 mm (4”) Wafer line
- Devices, materials and processes for
  - Microelectronics
  - Sensors and microsystems
  - Photovoltaic and optoelectronic devices
  - Graphene technology
CLEAN ROOM LAYOUT

CLEAN-ROOM FACILITIES

- Si and SiC thermal processes
- LPCVD and multichamber PECVD reactors
- Hot-wall and cold-wall CVD reactors
- Sputtering and evaporators
- Reactive Ion Etchers (RIE) and Deep RIE for Si and Silicon oxide
- Medium and high energy ion implanters
- Rapid Thermal Process systems
- Front and front-to-back side mask aligner
- Soft nanoimprint system and replication tools
- Wet anisotropic silicon etching (KOH, TMAH)
- Wafer bonder (anodic, fusion, SU-8, and glass frit)
- Wafer dicing and wire bonding system
- ZEISS CrossBeam 340 FIB/SEM with Raith EBL

500 m² (250 m² ISO 5) MEMS and CMOS Clean-Room
CLEAN ROOM - LITHOGRAPHY
CLEAN ROOM – WET AND DRY ETCHING
CLEAN ROOM – METAL DEPOSITION
CLEAN ROOM – GROWTH AND Annealing